Press Release

The Innovation Continues – Visit Viscom at APEX

Duluth, GA, January 2018 — **Viscom today announced plans to exhibit at the 2018 IPC APEX EXPO, scheduled to take place Feb. 27 - March 1, 2018 at the San Diego Convention Center in Ca. Constantly at the forefront of innovation for AOI, AXI and SPI, the company will show its X8011-II and X7056-II 3D X-ray inspection systems, along with the S3088 *ultra gold*, S3088 *ultra chrome* and S3088 SPI in Booth #1508.**

X8011-II PCB X-ray inspection

In modern SMD production, components such as BGAs, QFNs or QFPs are gaining ground. Because their connectors are mostly hidden, many solder joints can only be reliably checked with an X-ray inspection. The X8011-II PCB high resolution X-ray inspection system was developed especially for these tasks. Typical applications are, for example, the inspection of electronic assemblies and components, quality assurance in power electronics, or non-destructive special inspections.

X7056-II automatic 3D X-ray inspection

The X7056-II automatic 3D X-ray inspection system features extremely high throughput and superb image quality for the requirements in high-end electronics production. This new AXI in-line system can ensure precise inspection of hidden solder joints and components in high-volume production. It is equipped with the xFastFlow transport module, which cuts printed circuit board changing times. With this feature, up to three boards can be processed at the same time. The new handling design also means that significantly larger board sizes can be inspected and the scope of angled radiation is extended.

S3088 *ultra chrome* 3D AOI

The S3088 *ultra chrome* addresses the growing demand for reliable and easy-to-use 3D AOI technology at an economical price. Viscom's powerful approach is a combination of high quality, cost-effective machine design and standardized features. One orthogonal and eight angled view cameras provide full 3D defect detection coverage for components and solder joints on PCBs. The orthogonal optical resolution is switchable between 20 and 10 µm/pixel and also ready-made to inspect small components.

S3088 *ultra gold* 3D AOI

As one of the leading manufacturers of high quality systems for optical and X-ray inspection in electronics manufacturing, Viscom is constantly driving new innovations. The central innovation on the S3088 *ultra gold* is the 3D camera module XMplus with more than 120 megapixels. This key element of the S3088 *ultra gold* is designed for one purpose: high performance. The image data rate is up to 3.6 gigapixels per second.

S3088 SPI inspection

The award-winning S3088 SPI inspection system combines the advantages of market-leading Viscom AOI systems with powerful 3D SPI sensor technology and inspects the solder paste deposits with the highest possible speed and precision. Even the most demanding assemblies with CSPs or micro BGAs and pad sizes of 01005 are reliably inspected.

About Viscom

Viscom AG develops, manufactures and sells high-quality inspection systems. The portfolio encompasses the complete bandwidth of optical and X-ray inspections. In the area of assembly inspection for electronics manufacturing, the company is among the leading suppliers worldwide. Viscom systems can be configured specific to the customer and can be interlinked. The company headquarters and manufacturing location is in Hanover, Germany. With a wide network of branches, applications centers, service support points and representatives, Viscom is represented internationally. Founded in 1984, since 2006 Viscom has been listed on the Frankfurt Stock Exchange (ISIN: DE0007846867). For additional information: www.viscom.com